# SPN4402W N-Channel Enhancement Mode MOSFET

## **DESCRIPTION**

The SPN4402W is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching.

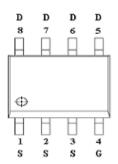
## **FEATURES**

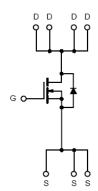
- 30V/12A,RDS(ON)=  $15m\Omega$ @VGS= 10V
- 30V/10A, RDS(ON)=  $18m\Omega$ @VGS= 4.5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ♦ SOP 8P package design

## **APPLICATIONS**

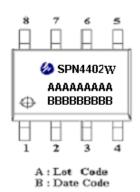
- Power Management in Note book
- Battery Powered System
- DC/DC Converter
- Load Switch
- LCD Display inverter

## PIN CONFIGURATION(SOP – 8P)





#### PART MARKING



II DESCRIPTION					
Pin	Symbol	Description			
1	S	Source			
2	S	Source			
3	S	Source			
4	G	Gate			
5	D	Drain			
6	D	Drain			
7	D	Drain			
8	D	Drain			

# **ORDERING INFORMATION**

Part Number	Package	Part Marking
SPN4402WS8RGB	SOP- 8P	SPN4402W

<sup>※</sup> SPN4402WS8RGB: 13" Tape Reel; Pb − Free; Halogen − Free

## ABSOULTE MAXIMUM RATINGS

(Ta=25°C Unless otherwise noted)

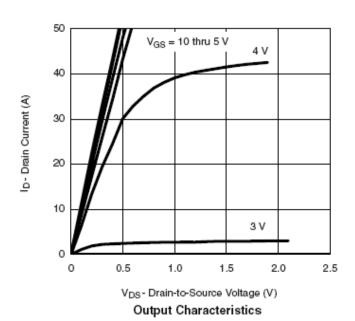
Parameter		Symbol	Typical	Unit
Drain-Source Voltage		Vdss	30	V
Gate –Source Voltage		VGSS	±20	V
Continuous Dusin Comment(Tr-150°C)	TA=25°C	In	12	A
Continuous Drain Current(TJ=150°€)	Ta=70°C	- Id	10	A
Pulsed Drain Current		IDM	30	A
Continuous Source Current(Diode Conduction)		Is	2.3	A
Decree Dissipation	TA=25°C	PD	2.5	W
Power Dissipation	Ta=70°C		1.6	W
Operating Junction Temperature		Тл	-55/150	$^{\circ}\mathbb{C}$
Storage Temperature Range		Tstg	-55/150	°C
Thermal Resistance-Junction to Ambient		RθJA	80	°C/W

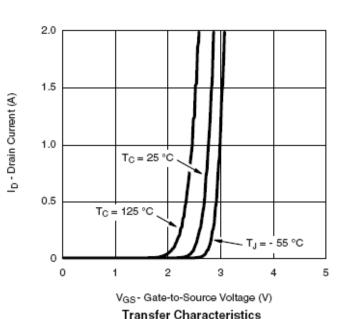
# **ELECTRICAL CHARACTERISTICS**

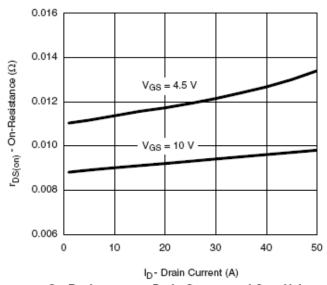
(TA=25°C Unless otherwise noted)

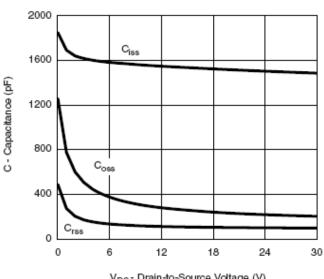
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS	V <sub>G</sub> S=0V,I <sub>D</sub> =250uA	30			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	0.6		1.8	] <b>v</b>	
Gate Leakage Current	Igss	V <sub>DS</sub> =0V,V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =24V,V <sub>GS</sub> =0V V <sub>DS</sub> =24V,V <sub>GS</sub> =0V T <sub>J</sub> =55°C			5	uA	
On-State Drain Current	ID(on)	V <sub>DS</sub> ≥5V,V <sub>GS</sub> =10V	25			A	
Drain-Source On-Resistance	RDS(on)	V <sub>GS</sub> = 10V,I <sub>D</sub> =12A V <sub>GS</sub> =4.5V,I <sub>D</sub> =10A		0.010 0.013	0.015 0.018	Ω	
Forward Transconductance	gfs	V <sub>DS</sub> =15V,I <sub>D</sub> =6.2A		13		S	
Diode Forward Voltage	Vsd	Is=2.3A,VGS =0V		0.5	1.0	V	
Dynamic	·						
Total Gate Charge	Qg			10	18		
Gate-Source Charge	Qgs	V <sub>DS</sub> =15V,V <sub>GS</sub> =10V I <sub>D</sub> = 2A		2.8		nC	
Gate-Drain Charge	Qgd			2.0			
Input Capacitance	Ciss			850		pF	
Output Capacitance	Coss	V <sub>DS</sub> =15V <sub>GS</sub> =0V f=1MHz		158			
Reverse Transfer Capacitance	Crss			120			
Trans. On Times	td(on)			10	15	nS	
Turn-On Time	tr	$V_{DD}=15V_{,RL}=15\Omega$		4	12		
T Off Time	td(off)	$I_{D}=5.0A, V_{GEN}=10V$ $R_{G}=1\Omega$		15	30		
Turn-Off Time	tf			10	15		

## TYPICAL CHARACTERISTICS









On-Resistance vs. Drain Current and Gate Voltage

V<sub>DS</sub>- Drain-to-Source Voltage (V)

Capacitance

## TYPICAL CHARACTERISTICS

0.001

0

0.2

0.4

0.6

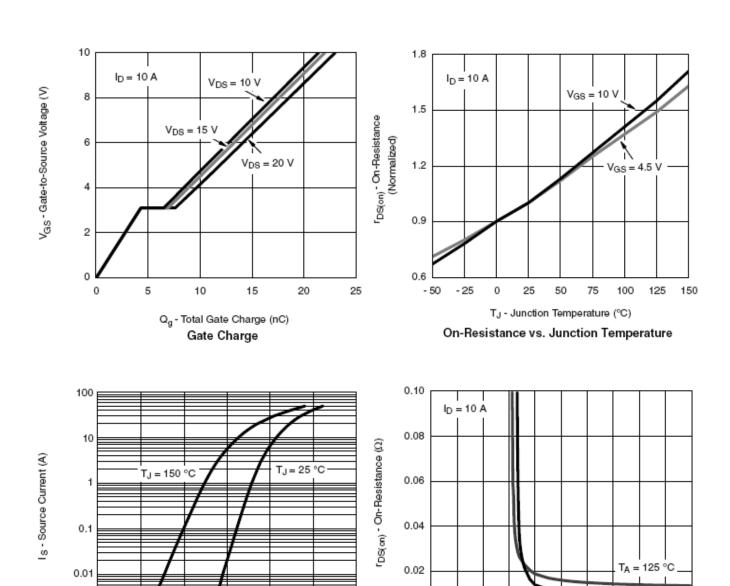
V<sub>SD</sub>- Source-to-Drain Voltage (V)

Source-Drain Diode Forward Voltage

0.8

1.0

1.2



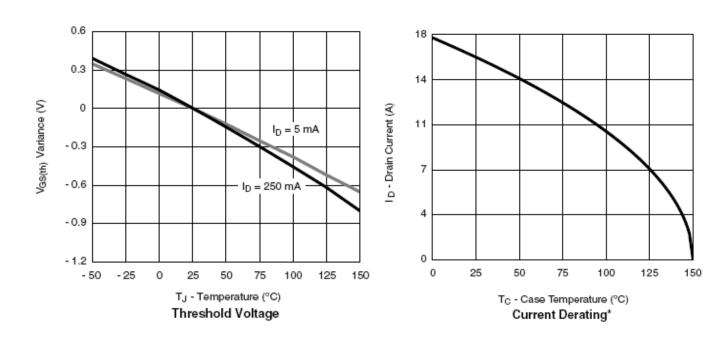
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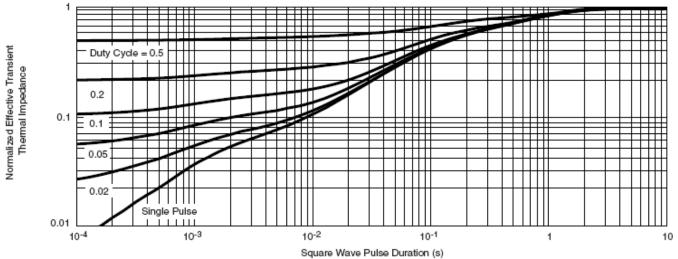
0

10

V<sub>GS</sub> - Gate-to-Source Voltage (V)
On-Resistance vs. Gate-to-Source Voltage

# TYPICAL CHARACTERISTICS

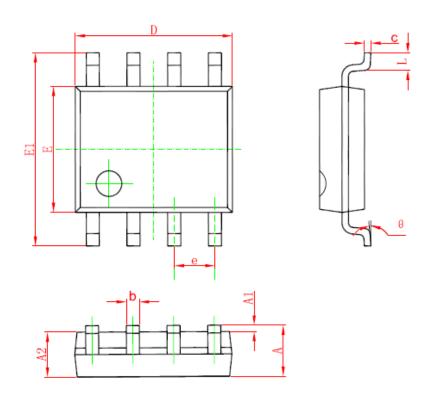




Normalized Thermal Transient Impedance, Junction-to-Case



# **SOP- 8 PACKAGE OUTLINE**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1. 350	1. 750	0.053	0.069	
A1	0. 100	0. 250	0.004	0.010	
A2	1. 350	1. 550	0.053	0.061	
b	0. 330	0. 510	0.013	0. 020	
С	0. 170	0. 250	0.006	0.010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0.150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	

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